



(43) International Publication Date
24 October 2013 (24.10.2013)

- (51) **International Patent Classification:**
H01L 33/48 (2010.01) *H01L 33/52* (2010.01)

(21) **International Application Number:**
PCT/US2013/037288

(22) **International Filing Date:**
19 April 2013 (19.04.2013)

(25) **Filing Language:** English

(26) **Publication Language:** English

(30) **Priority Data:**
61/687,240 20 April 2012 (20.04.2012) US

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(81) **Designated States** (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) **Designated States** (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— with international search report (Art. 21(3))

Published:

— with international search report (Art. 21(3))

(54) Title: LIGHT EMITTING DIODES AND A METHOD OF PACKAGING THE SAME

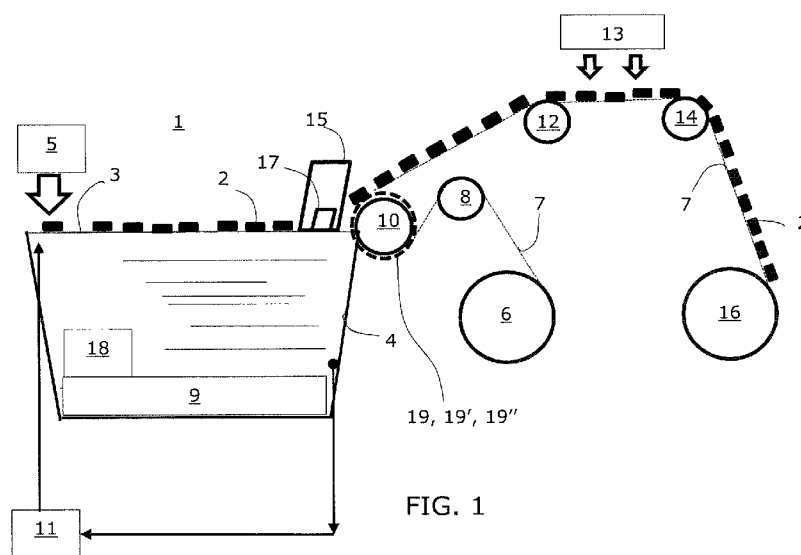


FIG. 1

(57) Abstract: Disclosed herein is a method of assembling an array of light emitting diode (LED) dies on a substrate comprising : positioning dies in fluid; exposing the dies to a magnetic force to attract the dies onto magnets that are arranged at pre-determined locations either on or near the substrate; and forming permanent connections between the dies and the substrate thereby constituting an array of LED dies on a substrate.